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2. The strapless lead frame according to Claim 1, wherein the semiconductor die has four sides and corners, and the lead frame leads are evenly distributed on each of the four sides and around the corners.

4. The strapless lead frame according to Claim 1, wherein said semiconductor die has a different number of bond pads on adjacent sides, and at least one of said bond pads is attached to a bond wire attached to a lead frame lead on a side of the lead frame adjacent to the side of the semiconductor die on which the bond pad is located.

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5. A strapless lead frame for use with heat slug packages, comprising:
a plurality of lead frame leads evenly distributed around a semiconductor die mount; and
a heat slug providing a rectangular die mount area, wherein said heat slug is attached under the lead frame with tape, there being the same number of lead frame leads on opposite sides of the lead frame and a different number of lead frame leads on adjacent sides of the lead frame.

6. The strapless lead frame according to Claim 5, including a semiconductor die with a different number of bond pads on adjacent sides and the same number of bond pads on opposite sides, and at least one of said bond pads is attached to a bond wire attached to a lead frame lead on a side of the lead frame adjacent to the side of the semiconductor die on which the bond pad is located.
